

Octal, 14-Bit, 65 MSPS Serial LVDS 1.8 V Analog-to-Digital Converter

FEATURES

- ▶ Low power: 55 mW per channel at 65 MSPS with scalable power options
- ▶ SNR = 75.5 dB (to Nyquist)
- ▶ SFDR = 91 dBc (to Nyquist)
- ▶ DNL = ± 0.6 LSB (typical), INL = ± 1.1 LSB (typical)
- ▶ Serial LVDS (ANSI-644, default)
 - ▶ Low power, reduced signal option (similar to IEEE 1596.3)
- ▶ Data and frame clock outputs
- ▶ 650 MHz full power analog bandwidth
- ▶ 2 V p-p input voltage range
- ▶ 1.8 V supply operation
- ▶ Serial port control
 - ▶ Full chip and individual channel power-down modes
 - ▶ Flexible bit orientation
 - ▶ Built-in and custom digital test pattern generation
 - ▶ Programmable clock and data alignment
 - ▶ Programmable output resolution
 - ▶ Standby mode

COMMERCIAL SPACE FEATURES

- ▶ Military temperature range (-55°C to $+125^{\circ}\text{C}$)
- ▶ Wafer diffusion lot traceability
- ▶ Radiation lot acceptance test (RLAT)
 - ▶ Total ionizing dose (TID)
- ▶ Radiation benchmark
 - ▶ Single event latch-up (SEL)

APPLICATIONS

- ▶ Low Earth orbit (LEO) space payloads
- ▶ Quadrature and diversity radio receiver
- ▶ Optical imaging

GENERAL DESCRIPTION

The AD9257S-CSL is an octal, 14-bit, 65 MSPS analog-to-digital converter (ADC) with an on-chip sample-and-hold circuit designed for low cost, low power, small size, and ease of use. The product operates at a conversion rate of up to 65 MSPS and is optimized for outstanding dynamic performance and low power in applications where a small package size is critical.

The ADC requires a single 1.8 V power supply and low voltage, positive emitter-coupled logic (LVPECL)/CMOS/low voltage differential signaling (LVDS)-compatible sample rate clock for full performance operation. No external reference or driver components are required for many applications.

The ADC automatically multiplies the sample rate clock for the appropriate LVDS serial data rate. A data clock output (DCO) for capturing data on the output and a frame clock output (FCO) for signaling a new output byte are provided. Individual channel power-down is supported and typically consumes 1 mW when all channels are disabled. The ADC contains several features designed to maximize flexibility and minimize system cost, such as programmable clock and data alignment and programmable digital test pattern generation. The available digital test patterns include built-in deterministic and pseudorandom patterns, along with custom user-defined test patterns entered via the serial port interface (SPI).

The AD9257S-CSL is available in an RoHS-compliant, 64-lead lead frame chip scale package (LFCSP). The device is specified over the -55°C to $+125^{\circ}\text{C}$ temperature range. This product is protected by a U.S. patent. Additional application and technical information can be found in the [Commercial Space Products Program](#) brochure and the [AD9257](#) data sheet.

PRODUCT HIGHLIGHTS

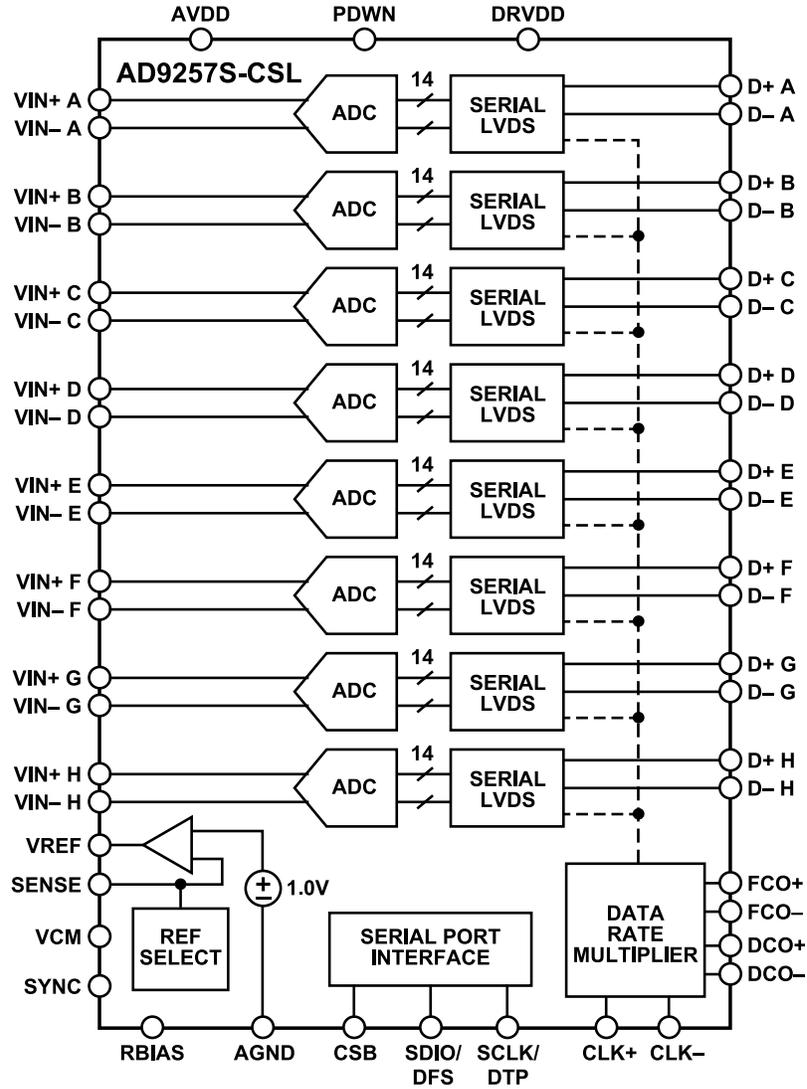
1. Small Footprint. Eight ADCs are contained in a small, space-saving package.
2. Low Power of 55 mW/Channel at 65 MSPS with Scalable Power Options.
3. Ease of Use. A DCO is provided that operates at frequencies of up to 455 MHz and supports double data rate (DDR) operation.
4. User Flexibility. The SPI control offers a wide range of flexible features to meet specific system requirements.
5. Pin Compatible with the [AD9637](#) (12-Bit Octal ADC).

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REVISION HISTORY**10/2021—Revision 0: Initial Version**

FUNCTIONAL BLOCK DIAGRAM



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Figure 1.

SPECIFICATIONS

DC SPECIFICATIONS

AVDD = 1.8 V, DRVDD = 1.8 V, 2 V p-p differential input, 1.0 V internal reference, and analog input (A_{IN}) = -1.0 dBFS, unless otherwise noted.

Table 1.

Parameter ¹	Temperature	Min	Typ	Max	Unit
RESOLUTION		14			Bits
ACCURACY					
No Missing Codes	Full		Guaranteed		
Offset Error	Full	-0.7	-0.3	+0.1	% FSR
Offset Matching	Full	0	0.23	0.6	% FSR
Gain Error	Full	-7.0	-2.9	+1.0	% FSR
Gain Matching	Full	-1.0	+1.6	+5.0	% FSR
Differential Nonlinearity (DNL)	Full	-0.95	±0.6	+1.6	LSB
Integral Nonlinearity (INL)	Full	-4.5	±1.1	+4.5	LSB
TEMPERATURE DRIFT					
Offset Error	Full		±2		ppm/°C
INTERNAL VOLTAGE REFERENCE					
Output Voltage (1 V Mode)	Full	0.98	0.99	1.01	V
Load Regulation at 1.0 mA (Reference Voltage (V_{REF}) = 1 V)	Full		2		mV
Input Resistance	Full		7.5		kΩ
INPUT-REFERRED NOISE					
$V_{REF} = 1.0$ V	25°C		0.94		LSB rms
ANALOG INPUTS					
Differential Input Voltage ($V_{REF} = 1$ V)	Full		2		V p-p
Common-Mode Voltage	Full		0.9		V
Common-Mode Range	Full	0.5		1.3	V
Differential Input Resistance			5.2		kΩ
Differential Input Capacitance	Full		3.5		pF
POWER SUPPLY					
AVDD	Full	1.7	1.8	1.9	V
DRVDD	Full	1.7	1.8	1.9	V
AVDD Current (I_{AVDD})	Full		198	211	mA
DRVDD Current (I_{DRVDD}) (ANSI-644 Mode)	Full		60	93	mA
I_{DRVDD} (Reduced Range Mode)	25°C		45		mA
TOTAL POWER CONSUMPTION					
Total Power Dissipation (Eight Channels, ANSI-644 Mode)	Full		464	547	mW
Total Power Dissipation (Eight Channels, Reduced Range Mode)	25°C		437		mW
Power-Down Dissipation	25°C		1		mW
Standby Dissipation ²	25°C		92		mW

¹ See the [AN-835 Application Note](#), *Understanding High Speed ADC Testing and Evaluation*, for definitions and for details on how these tests were completed.

² Can be controlled via the SPI.

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AC SPECIFICATIONS

AVDD = 1.8 V, DRVDD = 1.8 V, 2 V p-p differential input, 1.0 V internal reference, and $A_{IN} = -1.0$ dBFS, unless otherwise noted. CLK divider = 8 used for typical characteristics at input frequency ≥ 19.7 MHz.

Table 2.

Parameter ¹	Temperature	Min	Typ	Max	Unit
SIGNAL-TO-NOISE RATIO (SNR)					
Input Frequency (f_{IN}) = 9.7 MHz	25°C		75.7		dBFS
$f_{IN} = 19.7$ MHz	Full	72.8	75.6		dBFS
$f_{IN} = 30.5$ MHz	25°C		75.5		dBFS
$f_{IN} = 63.5$ MHz	25°C		74.9		dBFS
$f_{IN} = 123.4$ MHz	25°C		73.2		dBFS
SIGNAL-TO-NOISE AND DISTORTION (SINAD) RATIO					
$f_{IN} = 9.7$ MHz	25°C		75.6		dBFS
$f_{IN} = 19.7$ MHz	Full	70.9	75.6		dBFS
$f_{IN} = 30.5$ MHz	25°C		75.4		dBFS
$f_{IN} = 63.5$ MHz	25°C		74.8		dBFS
$f_{IN} = 123.4$ MHz	25°C		72.8		dBFS
EFFECTIVE NUMBER OF BITS (ENOB)					
$f_{IN} = 9.7$ MHz	25°C		12.3		Bits
$f_{IN} = 19.7$ MHz	Full	11.5	12.3		Bits
$f_{IN} = 30.5$ MHz	25°C		12.2		Bits
$f_{IN} = 63.5$ MHz	25°C		12.1		Bits
$f_{IN} = 123.4$ MHz	25°C		11.8		Bits
SPURIOUS-FREE DYNAMIC RANGE (SFDR)					
$f_{IN} = 9.7$ MHz	25°C		96		dBc
$f_{IN} = 19.7$ MHz	Full	78	96		dBc
$f_{IN} = 30.5$ MHz	25°C		91		dBc
$f_{IN} = 63.5$ MHz	25°C		95		dBc
$f_{IN} = 123.4$ MHz	25°C		83		dBc
WORST HARMONIC (SECOND OR THIRD)					
$f_{IN} = 9.7$ MHz	25°C		-99		dBc
$f_{IN} = 19.7$ MHz	Full		-98	-78	dBc
$f_{IN} = 30.5$ MHz	25°C		-91		dBc
$f_{IN} = 63.5$ MHz	25°C		-98		dBc
$f_{IN} = 123.4$ MHz	25°C		-83		dBc
WORST OTHER (EXCLUDING SECOND OR THIRD)					
$f_{IN} = 9.7$ MHz	25°C		-96		dBc
$f_{IN} = 19.7$ MHz	Full		-96	-86	dBc
$f_{IN} = 30.5$ MHz	25°C		-98		dBc
$f_{IN} = 63.5$ MHz	25°C		-95		dBc
$f_{IN} = 123.4$ MHz	25°C		-94		dBc
TWO-TONE INTERMODULATION DISTORTION (IMD)— A_{IN1} AND $A_{IN2} = -7.0$ dBFS					
$f_{IN1} = 30$ MHz, $f_{IN2} = 32$ MHz	25°C		92		dBc
CROSSTALK ²					
Crosstalk (Overrange Condition) ³	25°C		-98		dB
	25°C		-94		dB
POWER SUPPLY REJECTION RATIO (PSRR) ⁴					
AVDD	25°C		52		dB
DRVDD			71		dB

SPECIFICATIONS

Table 2.

Parameter ¹	Temperature	Min	Typ	Max	Unit
ANALOG INPUT BANDWIDTH, FULL POWER	25°C		650		MHz

¹ See the [AN-835 Application Note](#), *Understanding High Speed ADC Testing and Evaluation*, for definitions and for details on how these tests were completed.

² Crosstalk is measured at 10 MHz with -1.0 dBFS analog input on one channel and no input on the adjacent channel.

³ Overage condition is 3 dB above the full-scale input range.

⁴ PSRR is measured by injecting a sinusoidal signal at 10 MHz to the power supply pin and measuring the output spur on the fast Fourier transform (FFT). PSRR is calculated as the ratio of the amplitudes of the spur voltage over the pin voltage, expressed in decibels.

DIGITAL SPECIFICATIONS

AVDD = 1.8 V, DRVDD = 1.8 V, 2 V p-p differential input, 1.0 V internal reference, and $A_{IN} = -1.0$ dBFS, unless otherwise noted.

Table 3.

Parameter ^{1, 2}	Temperature	Min	Typ	Max	Unit
CLOCK INPUTS (CLK+, CLK-)					
Logic Compliance			CMOS/LVDS/LVPECL		
Differential Input Voltage ³	Full	0.2		3.6	V p-p
Input Voltage Range	Full	AGND - 0.2		AVDD + 0.2	V
Input Common-Mode Voltage	Full		0.9		V
Input Resistance (Differential)	25°C		15		kΩ
Input Capacitance	25°C		4		pF
LOGIC INPUTS (PDWN, SYNC, SCLK)					
Logic 1 Voltage	Full	1.2		AVDD + 0.2	V
Logic 0 Voltage	Full	0		0.8	V
Input Resistance	25°C		30		kΩ
Input Capacitance	25°C		2		pF
LOGIC INPUT (CSB)					
Logic 1 Voltage	Full	1.2		AVDD + 0.2	V
Logic 0 Voltage	Full	0		0.8	V
Input Resistance	25°C		26		kΩ
Input Capacitance	25°C		2		pF
LOGIC INPUT (SDIO)					
Logic 1 Voltage	Full	1.2		AVDD + 0.2	V
Logic 0 Voltage	Full	0		0.8	V
Input Resistance	25°C		26		kΩ
Input Capacitance	25°C		5		pF
LOGIC OUTPUT (SDIO) ⁴					
Logic 1 Voltage (Output High Current (I_{OH}) = 800 μ A)	Full		1.79		V
Logic 0 Voltage (Output Low Current (I_{OL}) = 50 μ A)	Full			0.05	V
DIGITAL OUTPUTS (D \pm x), ANSI-644					
Logic Compliance			LVDS		
Differential Output Voltage (V_{OD})	Full	± 247	± 350	± 454	mV
Output Offset Voltage (V_{OS})	Full	1.13	1.21	1.38	V
Output Coding (Default)			Twos complement		

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Table 3.

Parameter ^{1, 2}	Temperature	Min	Typ	Max	Unit
DIGITAL OUTPUTS (D± x), LOW POWER, REDUCED SIGNAL OPTION					
Logic Compliance			LVDS		
Differential Output Voltage (V _{OD})	Full	±150	±200	±250	mV
Output Offset Voltage (V _{OS})	Full	1.13	1.21	1.38	V
Output Coding (Default)			Twos complement		

¹ See the [AN-835 Application Note, Understanding High Speed ADC Testing and Evaluation](#), for definitions and for details on how these tests were completed.

² When referencing a single function of a multifunction pin in the parameters, only the portion of the pin name that is relevant to the specification is listed. For full pin names of multifunction pins, refer to the [Pin Configuration and Function Descriptions](#) section.

³ This is specified for LVDS and LVPECL only.

⁴ This is specified for 13 SDIO/DFS pins sharing the same connection.

SWITCHING SPECIFICATIONS

AVDD = 1.8 V, DRVDD = 1.8 V, 2 V p-p differential input, 1.0 V internal reference, and A_{IN} = -1.0 dBFS, unless otherwise noted.

Table 4.

Parameter ^{1, 2}	Temperature	Min	Typ	Max	Unit
CLOCK ³					
Input Clock Rate	Full	10		520	MHz
Conversion Rate	Full	10		65	MSPS
Clock Pulse Width High (t _{EH})	Full		7.69		ns
Clock Pulse Width Low (t _{EL})	Full		7.69		ns
OUTPUT PARAMETERS ³					
Propagation Delay (t _{PD})	Full	1.5	2.3	3.1	ns
Rise Time (t _R) (20% to 80%)	Full		300		ps
Fall Time (t _F) (20% to 80%)	Full		300		ps
FCO Propagation Delay (t _{FCO})	Full	1.5	2.3	3.1	ns
DCO Propagation Delay (t _{CPD}) ⁴	Full		t _{FCO} + (t _{SAMPLE/28})		ns
DCO to Data Delay (t _{DATA}) ⁴	Full	(t _{SAMPLE/28}) - 300	(t _{SAMPLE/28})	(t _{SAMPLE/28}) + 300	ps
DCO to FCO Delay (t _{FRAME}) ⁴	Full	(t _{SAMPLE/28}) - 300	(t _{SAMPLE/28})	(t _{SAMPLE/28}) + 300	ps
Data to Data Skew (t _{DATA-MAX} - t _{DATA-MIN})	Full		±50	±200	ps
Wake-Up Time (Standby)	25°C		35		µs
Wake-Up Time (Power-Down) ⁵	25°C		375		µs
Pipeline Latency	Full		16		Clock cycles
APERTURE					
Aperture Delay (t _A)	25°C		1		ns
Aperture Uncertainty (Jitter)	25°C		0.1		ps rms
Out-of-Range Recovery Time	25°C		1		Clock cycles

¹ See the [AN-835 Application Note, Understanding High Speed ADC Testing and Evaluation](#), for definitions and for details on how these tests were completed.

² Measured on standard FR-4 material.

³ Can be adjusted via the SPI.

⁴ t_{SAMPLE/28} is based on the number of bits divided by 2 because the delays are based on half duty cycles. t_{SAMPLE} = 1/f_S.

⁵ Wake-up time is defined as the time required to return to normal operation from power-down mode.

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TIMING SPECIFICATIONS

Table 5.

Parameter	Description	Limit	Unit
SYNC TIMING REQUIREMENTS			
t_{SSYNC}	SYNC to rising edge of CLK+ setup time	0.24	ns typical
t_{HSYNC}	SYNC to rising edge of CLK+ hold time	0.40	ns typical
SPI TIMING REQUIREMENTS¹			
	See Figure 4		
t_{DS}	Setup time between the data and the rising edge of SCLK	2	ns minimum
t_{DH}	Hold time between the data and the rising edge of SCLK	2	ns minimum
t_{CLK}	Period of the SCLK	40	ns minimum
t_S	Setup time between CSB and SCLK	2	ns minimum
t_H	Hold time between CSB and SCLK	2	ns minimum
t_{HIGH}	SCLK pulse width high	10	ns minimum
t_{LOW}	SCLK pulse width low	10	ns minimum
t_{EN_SDIO}	Time required for the SDIO pin to switch from an input to an output relative to the SCLK falling edge (not shown in Figure 4)	10	ns minimum
t_{DIS_SDIO}	Time required for the SDIO pin to switch from an output to an input relative to the SCLK rising edge (not shown in Figure 4)	10	ns minimum

¹ When referring to a single function of a multifunction pin, only the portion of the pin name that is relevant to the specification is listed. For full pin names of multifunction pins, refer to the Pin Configuration and Function Descriptions section.

Timing Diagrams

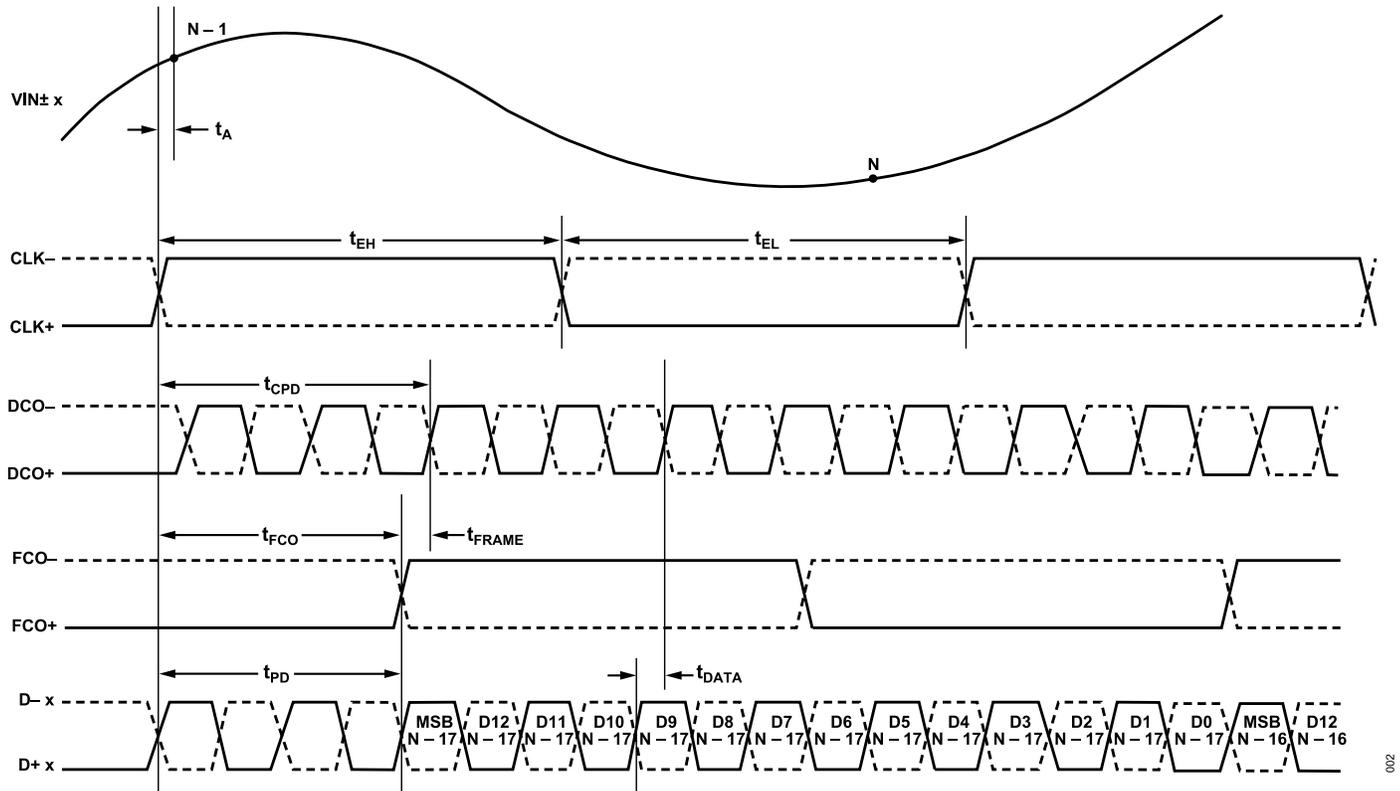


Figure 2. Word Wise DDR, 1x Frame, 14-Bit Output Mode (Default)

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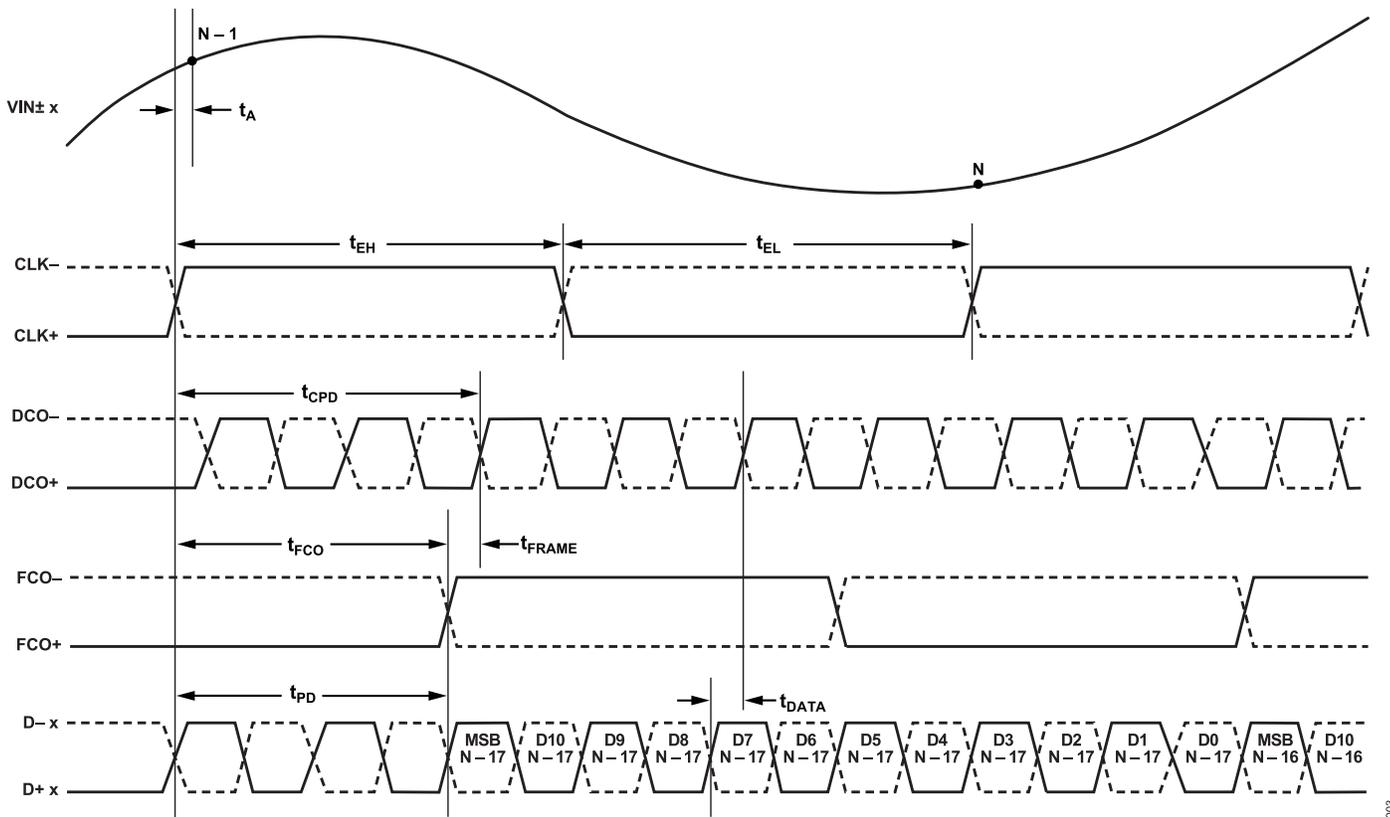


Figure 3. Word Wise DDR, 1x Frame, 12-Bit Output Mode

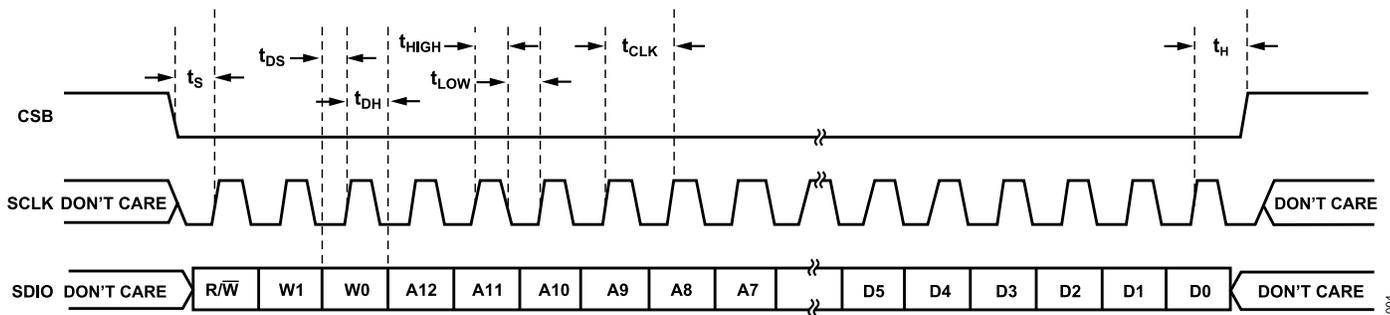


Figure 4. Serial Port Interface Timing Diagram

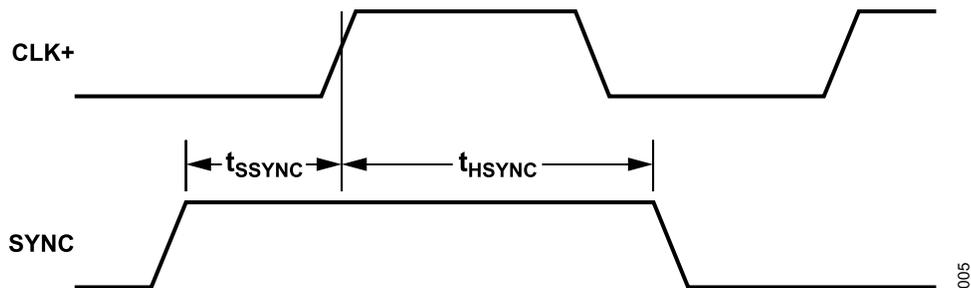


Figure 5. SYNC Input Timing Requirements

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RADIATION TEST AND LIMIT SPECIFICATIONS

AVDD = 1.8 V, DRVDD = 1.8 V, 2 V p-p differential input, 1.0 V internal reference, and $A_{IN} = -1.0$ dBFS, unless otherwise noted. CLK divider = 8 used for typical characteristics at input frequency ≥ 19.7 MHz. Total ionizing dose (TID) testing characterized to 45 krad (30 krad + 50% overstress) with biased annealing at 100°C for 168 hours. Once characterized, TID testing is performed to 30 krad only.

Table 6.

Parameter ¹	Temperature	Min	Typ	Max	Unit
ACCURACY					
Offset Error	25°C	-1.1		+0.2	% FSR
Offset Matching	25°C	0		0.8	% FSR
Gain Error	25°C	-10.0		+2.0	% FSR
Gain Matching	25°C	-2.0		+8.0	% FSR
Differential Nonlinearity (DNL)	25°C	-1.2		+1.8	LSB
Integral Nonlinearity (INL)	25°C	-7.0		+7.0	LSB
INTERNAL VOLTAGE REFERENCE					
Output Voltage (1 V Mode)	25°C	0.98		1.01	V
POWER SUPPLY					
AVDD Current (I_{AVDD})	25°C			232	mA
DRVDD Current (I_{DRVDD}) (ANSI-644 Mode)	25°C			102	mA
TOTAL POWER CONSUMPTION					
Total Power Dissipation (Eight Channels, ANSI-644 Mode)	25°C			700	mW
Power-Down Dissipation	25°C			12	mW
Standby Dissipation ²	25°C			139	mW
SIGNAL-TO-NOISE RATIO (SNR)					
$f_{IN} = 19.7$ MHz	25°C	56.0			dBFS
SIGNAL-TO-NOISE AND DISTORTION (SINAD) RATIO					
$f_{IN} = 19.7$ MHz	25°C	54.0			dBFS
SPURIOUS-FREE DYNAMIC RANGE (SFDR)					
$f_{IN} = 19.7$ MHz	25°C	57			dBc
WORST HARMONIC (SECOND OR THIRD)					
$f_{IN} = 19.7$ MHz	25°C			-59	dBc
WORST OTHER (EXCLUDING SECOND OR THIRD)					
$f_{IN} = 19.7$ MHz	25°C			-62	dBc

¹ See the [AN-835 Application Note](#), *Understanding High Speed ADC Testing and Evaluation*, for definitions and for details on how these tests were completed.

² Can be controlled via the SPI.

ABSOLUTE MAXIMUM RATINGS

Table 7.

Parameter	Rating
Electrical	
AVDD to AGND	-0.3 V to +2.0 V
DRVDD to AGND	-0.3 V to +2.0 V
Digital Outputs (D± x, DCO+, DCO-, FCO+, FCO-) to AGND	-0.3 V to +2.0 V
CLK+, CLK- to AGND	-0.3 V to +2.0 V
VIN+ x, VIN- x to AGND	-0.3 V to +2.0 V
SCLK/DTP, SDIO/DFS, CSB to AGND	-0.3 V to +2.0 V
SYNC, PDWN to AGND	-0.3 V to +2.0 V
RBIAS to AGND	-0.3 V to +2.0 V
VREF, SENSE to AGND	-0.3 V to +2.0 V
Environmental	
Operating Temperature Range (Ambient)	-55°C to +125°C
Maximum Junction Temperature	150°C
Lead Temperature (Soldering, 10 sec)	300°C
Storage Temperature Range (Ambient)	-65°C to +150°C

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL CHARACTERISTICS

The exposed pad must be soldered to the ground plane for the LFCSP. Soldering the exposed pad to the printed circuit board (PCB) increases the reliability of the solder joints and maximizes the thermal capability of the package.

Table 8. Thermal Resistance¹

Package Type	Airflow Velocity (m/sec)	$\theta_{JA}^{2,3}$	$\theta_{JC}^{2,4}$	$\theta_{JB}^{2,5}$	$\Psi_{JT}^{2,3}$	Unit
	1.0	19.5	N/A	11.8	0.2	°C/W
	2.5	17.5	N/A	N/A	0.2	°C/W

¹ N/A means not applicable.

² Per JEDEC 51-7, plus JEDEC 25-5 2S2P test board.

³ Per JEDEC JESD51-2 (still air) or JEDEC JESD51-6 (moving air).

⁴ Per MIL-Std 883, Method 1012.1.

⁵ Per JEDEC JESD51-8 (still air).

Typical θ_{JA} is specified for a 4-layer PCB with a solid ground plane. As shown in Table 8, airflow improves heat dissipation, which reduces θ_{JA} . In addition, metal in direct contact with the package leads from metal traces, through holes, ground, and power planes reduces θ_{JA} .

OUTGAS TESTING

The criteria used for the acceptance and rejection of materials must be determined by the user and based upon specific component and system requirements. Historically, a total mass loss (TML) of 1.00% and collected volatile condensable material (CVCM) of 0.10% have been used as screening levels for rejection of spacecraft materials.

Table 9. Outgas Testing

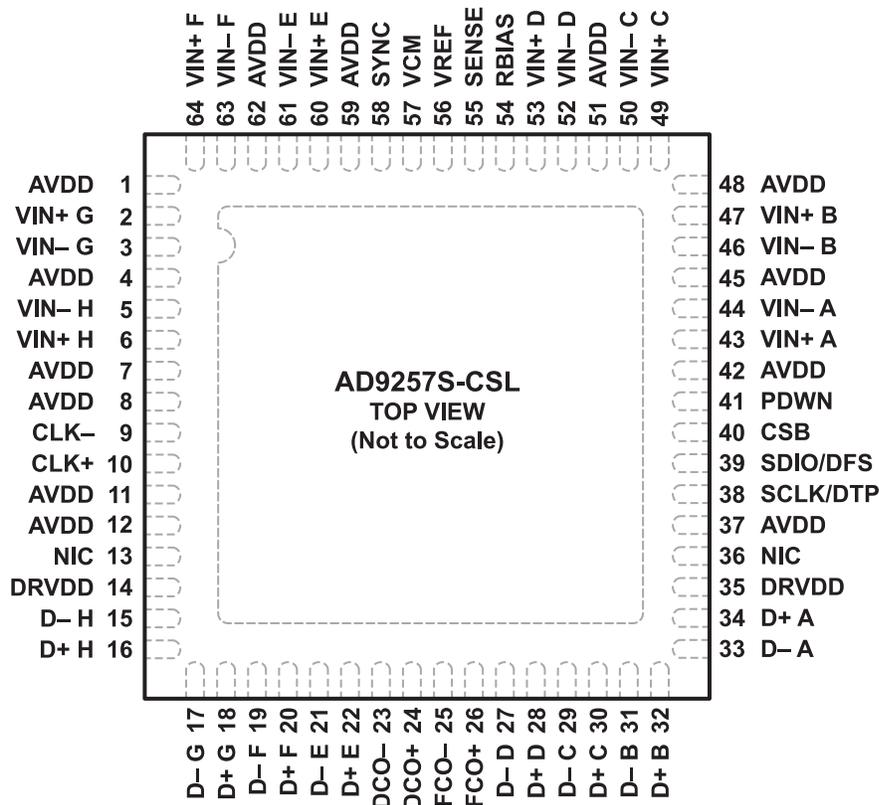
Specification (Tested per ASTM E595-15)	Value	Unit
Total Mass Lost	0.06	%
Collected Volatile Condensable Material	0.01	%
Water Vapor Recovered	0.03	%

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



NOTES

1. NIC = NOT INTERNALLY CONNECTED. THESE PINS CAN BE CONNECTED TO GROUND.
2. THE EXPOSED THERMAL PAD ON THE BOTTOM OF THE PACKAGE PROVIDES THE ANALOG GROUND FOR THE DEVICE. THIS EXPOSED PAD MUST BE CONNECTED TO GROUND FOR PROPER OPERATION.

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Figure 6. Pin Configuration, Top View

Table 10. Pin Function Descriptions

Pin No.	Mnemonic	Description
0	AGND, Exposed Pad	Analog Ground, Exposed Pad. The exposed thermal pad on the bottom of the package provides the analog ground for the device. This exposed pad must be connected to ground for proper operation.
1, 4, 7, 8, 11, 12, 37, 42, 45, 48, 51, 59, 62	AVDD	1.8 V Analog Supply.
13, 36	NIC	Not Internally Connected. These pins can be connected to ground.
14, 35	DRVDD	1.8 V Digital Output Driver Supply.
2, 3	VIN+ G, VIN- G	ADC G Analog Input True, ADC G Analog Input Complement.
5, 6	VIN- H, VIN+ H	ADC H Analog Input Complement, ADC H Analog Input True.
9, 10	CLK-, CLK+	Input Clock Complement, Input Clock True.
15, 16	D- H, D+ H	ADC H Digital Output Complement, ADC H Digital Output True.
17, 18	D- G, D+ G	ADC G Digital Output Complement, ADC G Digital Output True.
19, 20	D- F, D+ F	ADC F Digital Output Complement, ADC F Digital Output True.
21, 22	D- E, D+ E	ADC E Digital Output Complement, ADC E Digital Output True.
23, 24	DCO-, DCO+	Data Clock Digital Output Complement, Data Clock Digital Output True.
25, 26	FCO-, FCO+	Frame Clock Digital Output Complement, Frame Clock Digital Output True.
27, 28	D- D, D+ D	ADC D Digital Output Complement, ADC D Digital Output True.
29, 30	D- C, D+ C	ADC C Digital Output Complement, ADC C Digital Output True.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

Table 10. Pin Function Descriptions

Pin No.	Mnemonic	Description
31, 32	D- B, D + B	ADC B Digital Output Complement, ADC B Digital Output True.
33, 34	D- A, D+ A	ADC A Digital Output Complement, ADC A Digital Output True.
38	SCLK/DTP	Serial Clock (SCLK)/Digital Test Pattern (DTP).
39	SDIO/DFS	Serial Data Input/Output (SDIO)/Data Format Select (DFS).
40	CSB	Chip Select Bar.
41	PDWN	Power-Down.
43, 44	VIN+ A, VIN- A	ADC A Analog Input True, ADC A Analog Input Complement.
46, 47	VIN- B, VIN+ B	ADC B Analog Input Complement, ADC B Analog Input True.
49, 50	VIN+ C, VIN- C	ADC C Analog Input True, ADC C Analog Input Complement.
52, 53	VIN- D, VIN+ D	ADC D Analog Input Complement, ADC D Analog Input True.
54	RBIAS	Analog Current Bias Setting. Connect to 10 k Ω (1% tolerance) resistor to ground.
55	SENSE	Reference Mode Selection.
56	VREF	Voltage Reference Input/Output.
57	VCM	Analog Output Voltage at Midsupply. Sets common mode of the analog inputs.
58	SYNC	Digital Input. SYNC input to clock divider. 30 k Ω internal pull-down.
60, 61	VIN+ E, VIN- E	ADC E Analog Input True, ADC E Analog Input Complement.
63, 64	VIN- F, VIN+ F	ADC F Analog Input Complement, ADC F Analog Input True.

TYPICAL PERFORMANCE CHARACTERISTICS

See the [AD9257](#) data sheet for a full set of Typical Performance Characteristics plots.

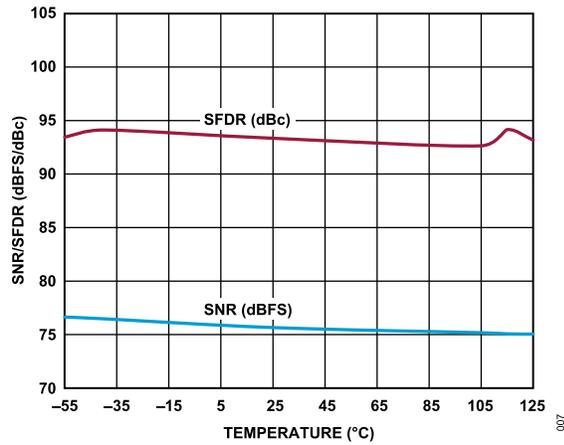
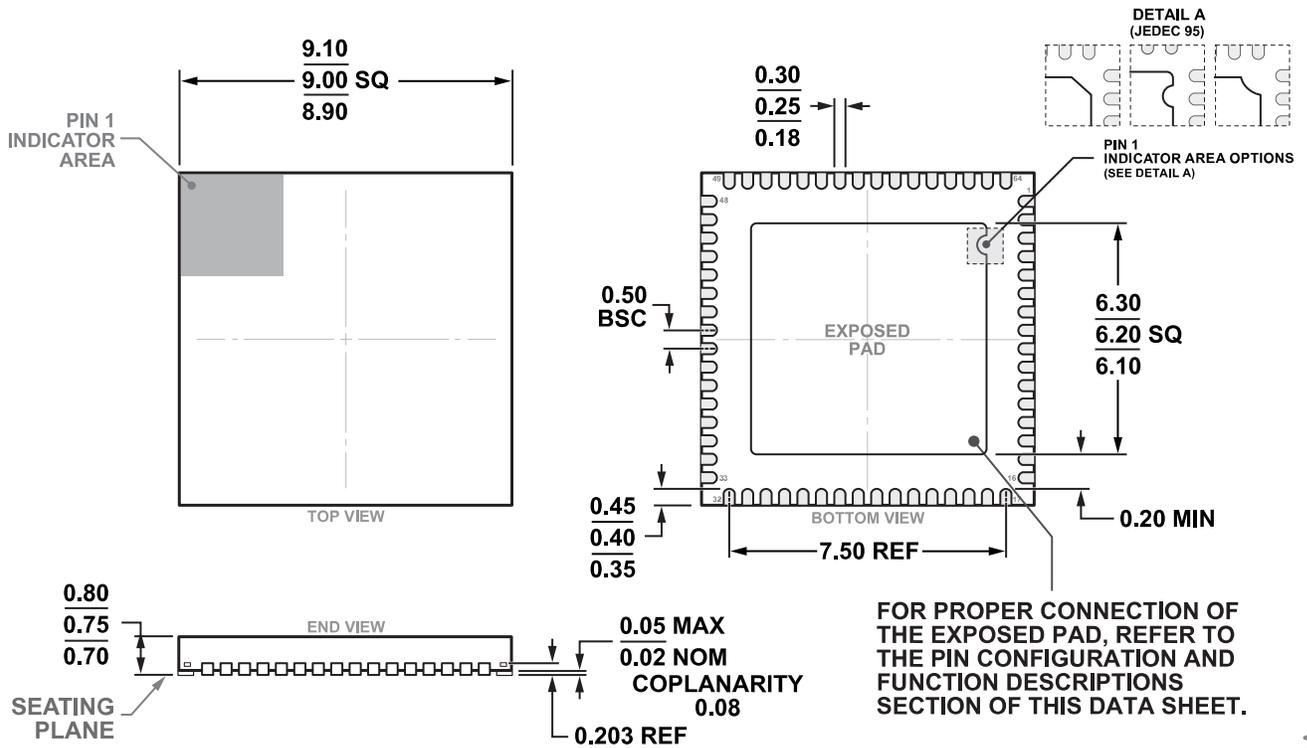


Figure 7. SNR/SFDR vs. Temperature, $f_{IN} = 9.7$ MHz, Sample Frequency (f_{SAMPLE}) = 65 MSPS

OUTLINE DIMENSIONS



PKG-004559

10-26-2018-A

COMPLIANT TO JEDEC STANDARDS MO-220-WMMD

Figure 8. 64-Lead Lead Frame Chip Scale Package [LFCSP]
9 mm × 9 mm Body and 0.75 mm Package Height
(CP-64-17)
Dimensions shown in millimeters

Updated: September 29, 2021

ORDERING GUIDE

Model ¹	Temperature Range	Package Description	Packing Quantity	Package Option
AD9257TCPZ-65-CSL	-55°C to +125°C	64-Lead LFCSP (9 mm × 9 mm × 0.75 mm w/ EP)	Tray, 260	CP-64-17

¹ Z = RoHS Compliant Part.